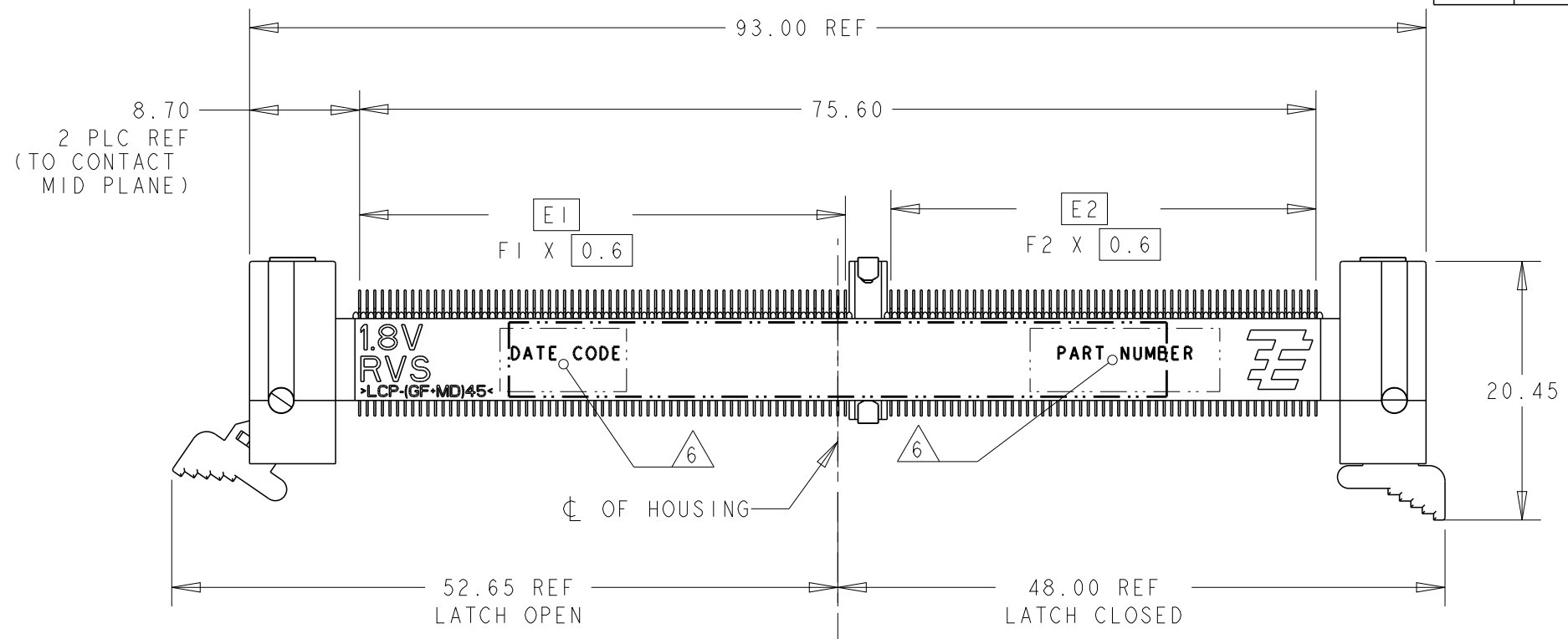


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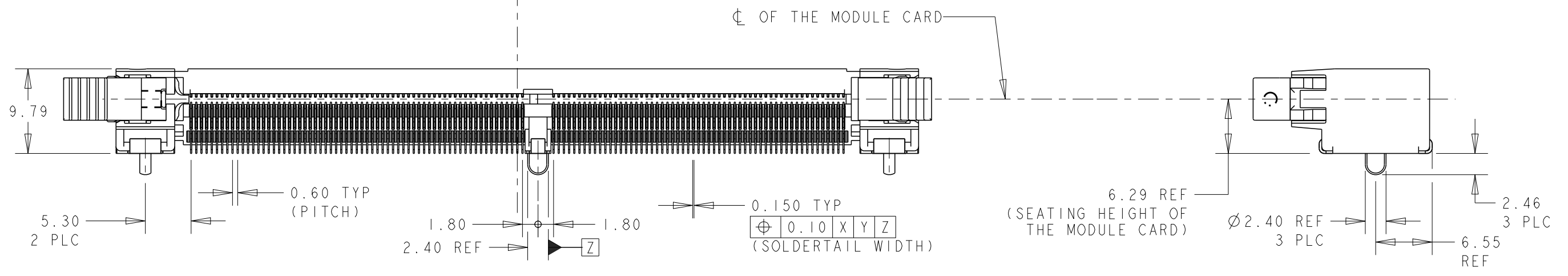
LOC  
DY

DIST  
-

REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	B5	REVISED PER ECR-11-022142	01NOV2011	SYJ	LSF



- 1 MATERIAL: HOUSING: HIGH TEMP LCP, BLACK, UL94V-0  
LATCHES: HIGH TEMP LCP, NATURAL, UL94V-0  
CONTACTS: COPPER ALLOY  
SOLDERPEGS: COPPER ALLOY
- 2 FINISH: ENGAGEMENT AREAS: 0.76µm MIN GOLD OVER  
1.25µm MIN NICKEL  
SOLDERTAILS: 0.02µm MIN GOLD OVER  
1.25µm MIN NICKEL
- 3 FINISH: ENGAGEMENT AREAS: 0.38µm MIN GOLD OVER  
1.25µm MIN NICKEL  
SOLDERTAILS: 0.02µm MIN GOLD OVER  
1.25µm MIN NICKEL
- 4. ACCEPTS 1.0mm THICK MEMORY MODULE, PER JEDEC MO-244, WITH BEVELS (FOR INSERTION LEAD-IN) REQUIRED.
- 5. PRODUCT SHALL BE PACKED IN JEDEC HARD TRAY (BLACK).
- 6 PART NUMBER AND DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN. DATE CODE FORMAT: YYWWD.



64	56	38.4	33.6	45.5	40.7	DDR3 (AB/BB/CB) ; STD	1.5V	3	1- -4
64	56	38.4	33.6	45.5	40.7	DDR2 (AA/BA/CA) ; STD	1.8V	3	1- -3
56	64	33.6	38.4	40.7	45.5	DDR3 (AB/BB/CB) ; RVS	1.5V	3	1- -2
56	64	33.6	38.4	40.7	45.5	DDR2 (AA/BA/CA) ; RVS	1.8V	3	1- -1
64	56	38.4	33.6	45.5	40.7	DDR3 (AB/BB/CB) ; STD	1.5V	2	-4
64	56	38.4	33.6	45.5	40.7	DDR2 (AA/BA/CA) ; STD	1.8V	2	-3
56	64	33.6	38.4	40.7	45.5	DDR3 (AB/BB/CB) ; RVS	1.5V	2	-2
56	64	33.6	38.4	40.7	45.5	DDR2 (AA/BA/CA) ; RVS	1.8V	2	-1
F2	F1	E2	E1	B2	B1	VARIATION ; ORIENTATION MODULE	VOLTAGE MARKING	CONTACT FINISH	P/N

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DWN WYLEE 18MAY2007  
 CHK YJ SEE  
 APVD SF LEONG  
 PRODUCT SPEC 108-51091  
 APPLICATION SPEC 114-51011  
 WEIGHT -

**STE** TE CONNECTIVITY Singapore

NAME ASSEMBLY, MINIDIMM, R/A, LF  
 0.60mm PITCH, 244 CKTS, DDR2/3

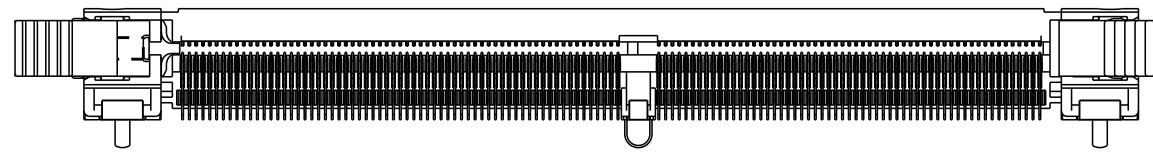
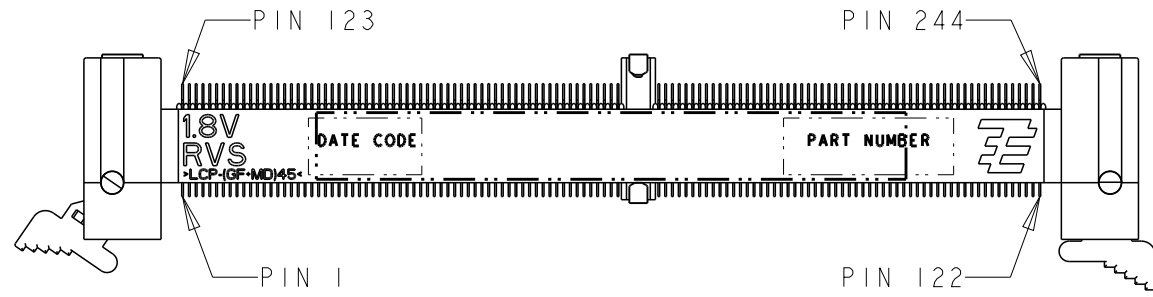
SIZE A3 CAGE CODE 00779 DRAWING NO C-1735438

CUSTOMER DRAWING SCALE 1:1 SHEET 1 OF 5 REV B5

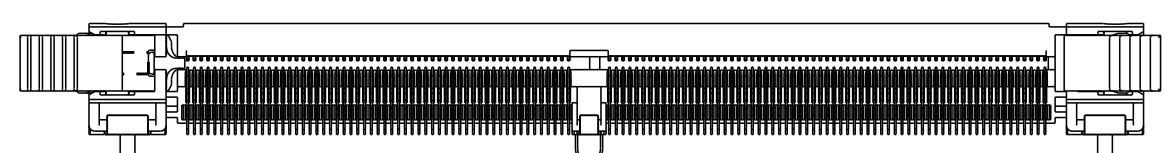
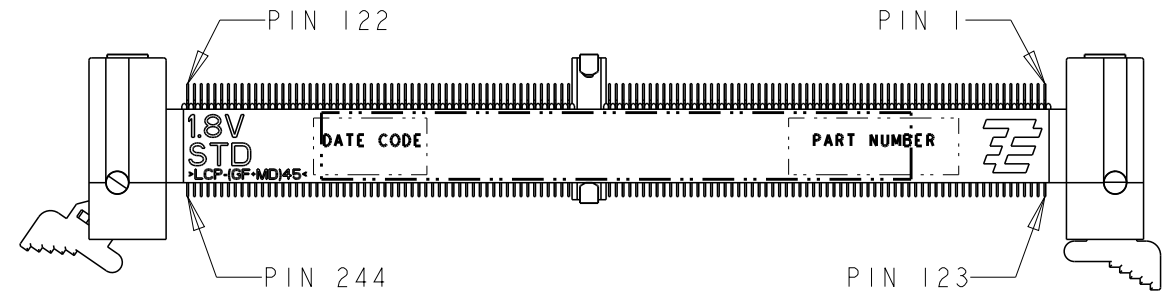
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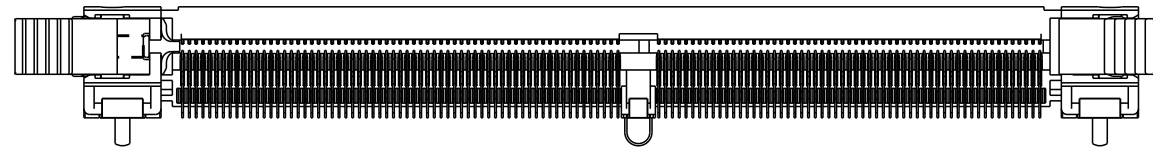
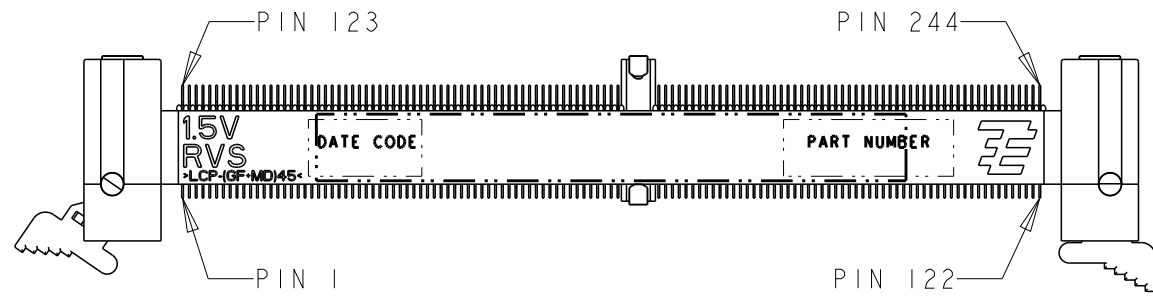
LOC	DIST	REVISIONS					
DY	-	P	LTR	DESCRIPTION	DATE	DWN	APVD
		-		SEE SHEET 1	-	-	-



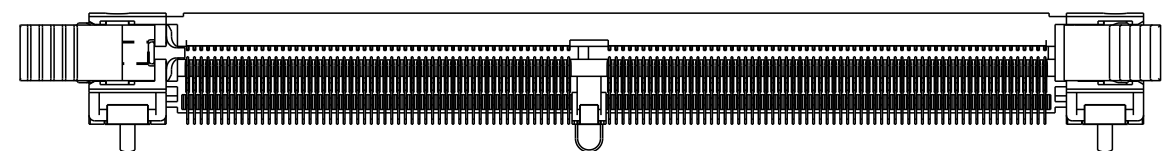
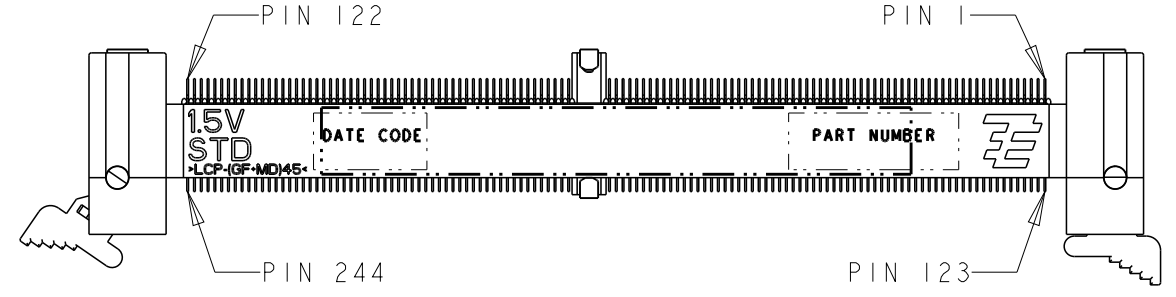
P/N X- -1  
(1.8V RVS)  
SCALE 3:2



P/N X- -3  
(1.8V STD)  
SCALE 3:2

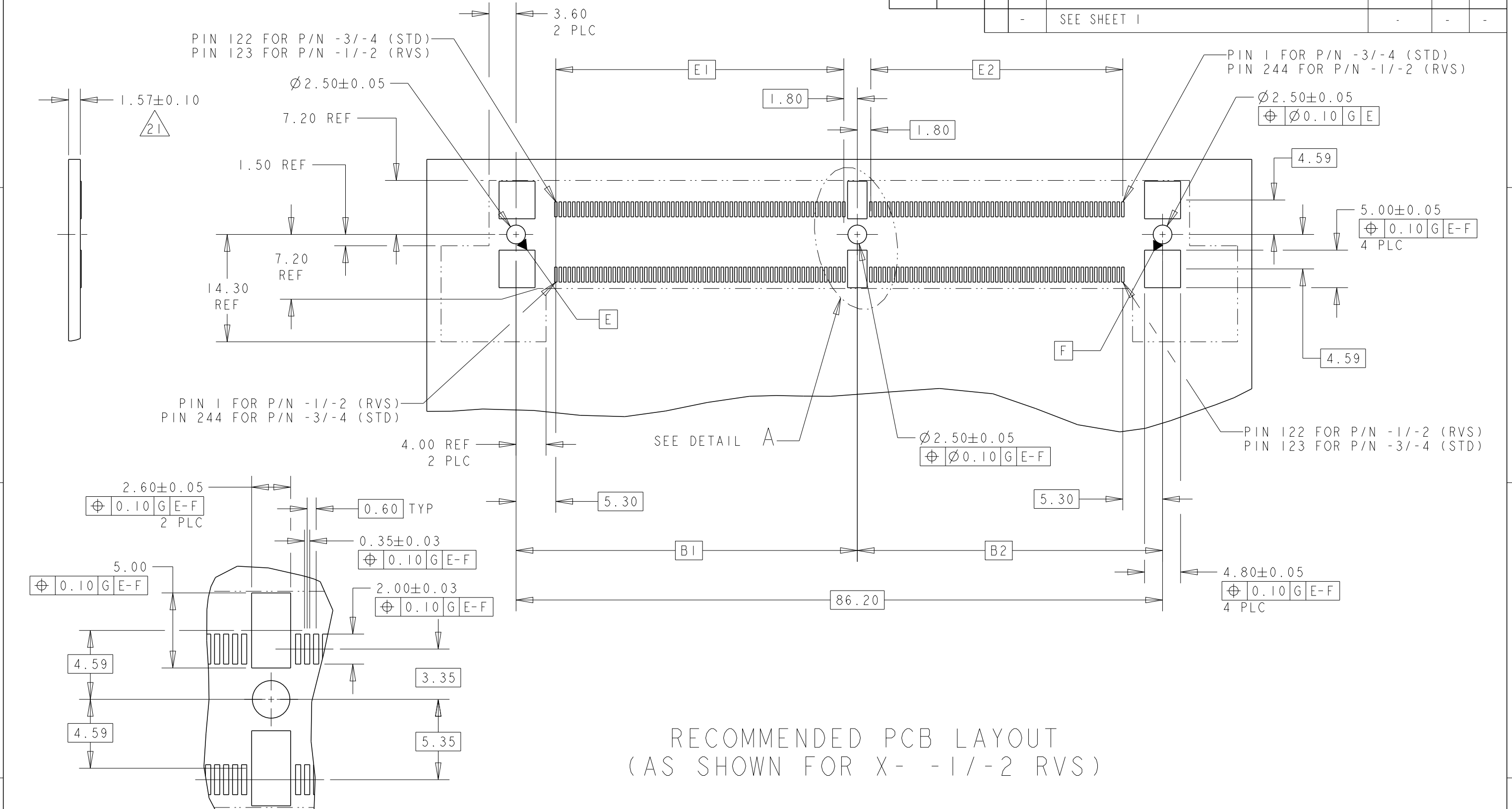


P/N X- -2  
(1.5V RVS)  
SCALE 3:2




P/N X- -4  
(1.5V STD)  
SCALE 3:2

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DIMENSIONS: mm		CHK YJ SEE	NAME ASSEMBLY, MINIDIMM, R/A, LF 0.60mm PITCH, 244 CKTS, DDR2/3		
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ±0.25 2 PLC ±0.13 3 PLC ±0.10 4 PLC ± ANGLES ±1°		APVD SF LEONG			
MATERIAL		PRODUCT SPEC 108-51091	SIZE A3	CAGE CODE 00779	DRAWING NO C-1735438
FINISH SEE P/N TABLE		APPLICATION SPEC 114-51011	WEIGHT -	SCALE 3:2	SHEET 2 OF 5
		CUSTOMER DRAWING	REV B5		



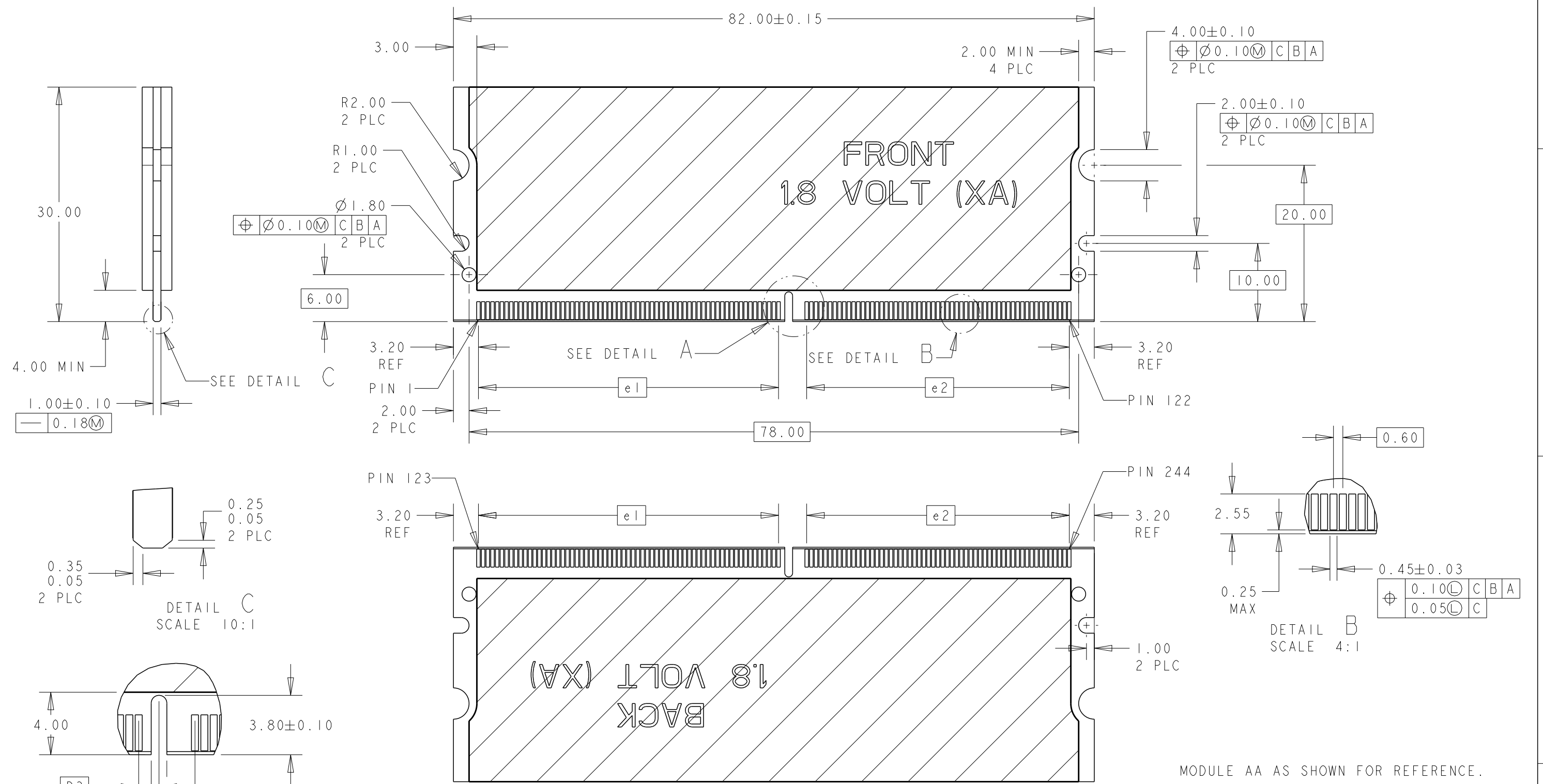
RECOMMENDED PCB LAYOUT  
(AS SHOWN FOR X- -1/-2 RVS)

DETAIL A  
SCALE 4:1

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DIMENSIONS: mm		CHK YJ SEE	NAME ASSEMBLY, MINIDIMM, R/A, LF 0.60mm PITCH, 244 CKTS, DDR2/3	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±.25 1 PLC ±0.25 2 PLC ±0.13 3 PLC ±0.10 4 PLC ±. ANGLES ±1°		APVD SF LEONG	PRODUCT SPEC 108-51091	
MATERIAL		APPLICATION SPEC 114-51011	DRAWING NO C=1735438	
FINISH		WEIGHT -	SIZE A3	CAGE CODE 00779
		CUSTOMER DRAWING	SCALE 2:1	SHEET 3 OF 5
				REV B5

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LOC DY	DIST -	REVISIONS		
P	LTR	DESCRIPTION	DATE	DWN
-	-	SEE SHEET 1	-	-



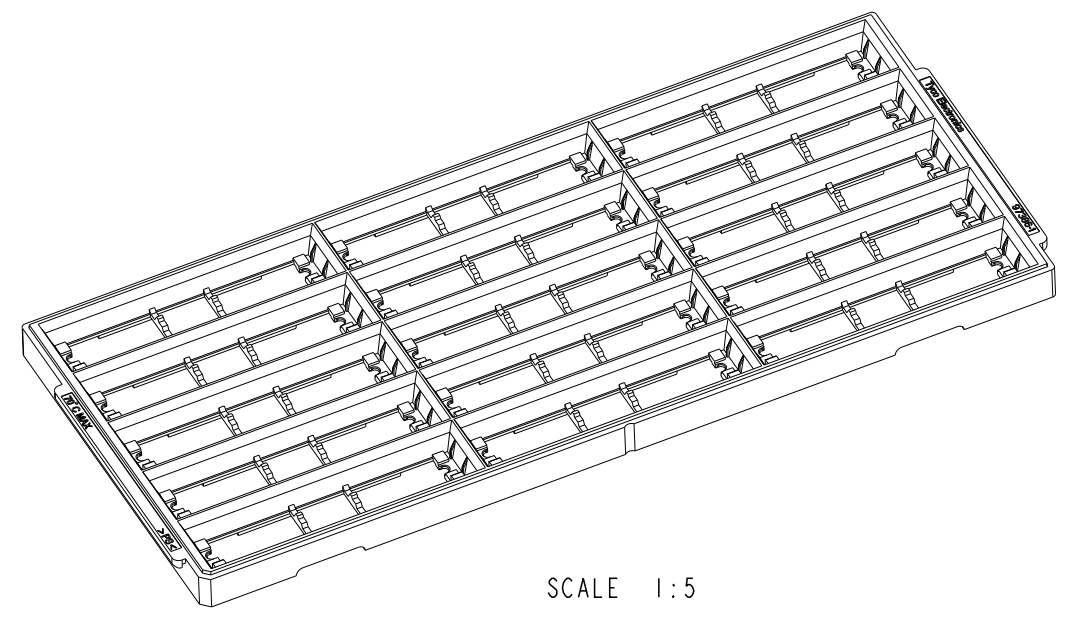
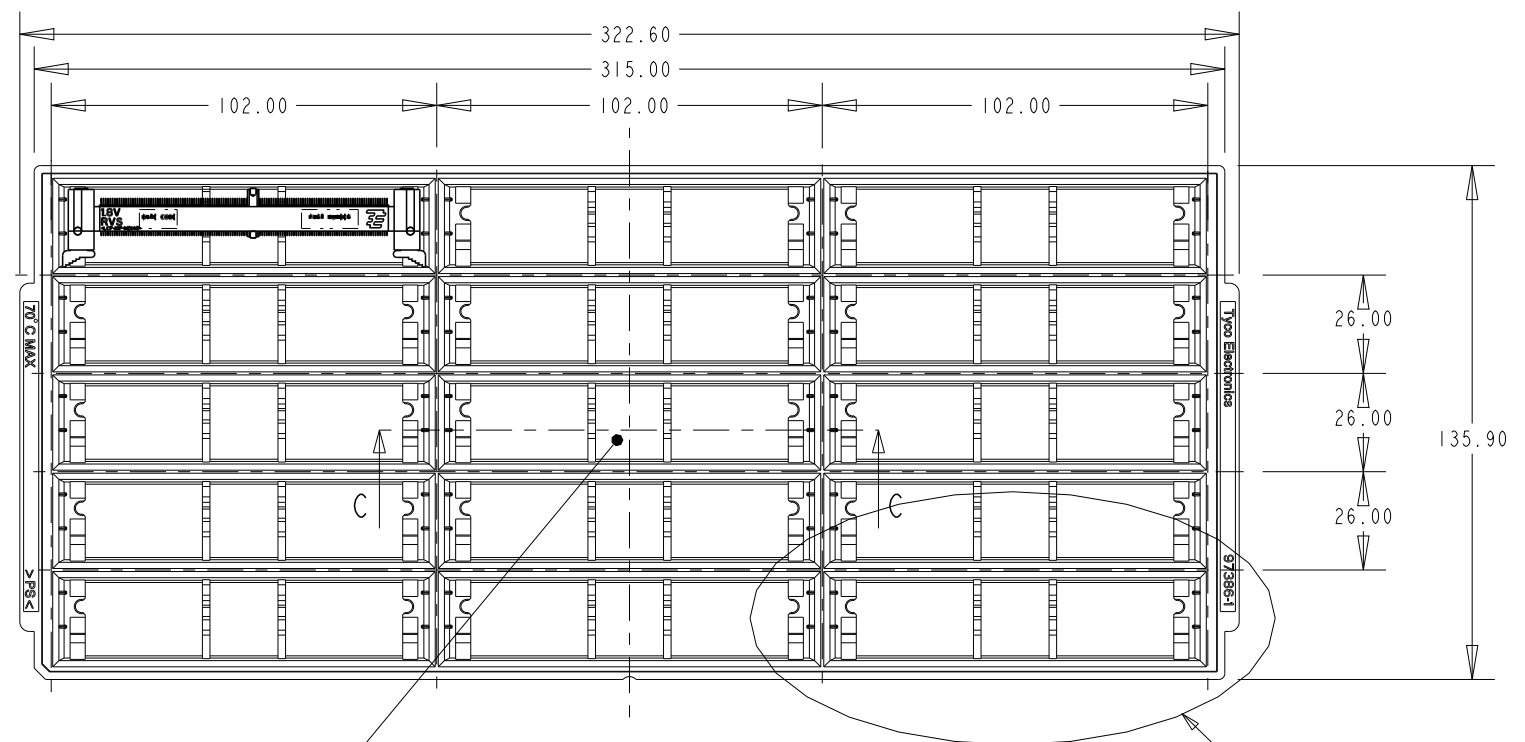
FOR P/N X- -2 AND X- -4.	2.3	33.6	38.4	1.5V	AB/BB/CB
FOR P/N X- -1 AND X- -3.	1.3	33.6	38.4	1.8V	AA/BA/CA
REMARKS	D3	e2	e1	VOLTAGE MARKING	MODULE VARIATION

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DWN WYLEE	18MAY2007	<b>STE</b> TE CONNECTIVITY Singapore
CHK YJ SEE		
APVD SF LEONG		NAME ASSEMBLY, MINIDIMM, R/A, LF 0.60mm PITCH, 244 CKTS, DDR2/3
PRODUCT SPEC 108-51091		SIZE A3
APPLICATION SPEC 114-51011		CAGE CODE 00779
WEIGHT -		DRAWING NO C-1735438
CUSTOMER DRAWING		SCALE 1:1
		SHEET 4 OF 5
		REV B5

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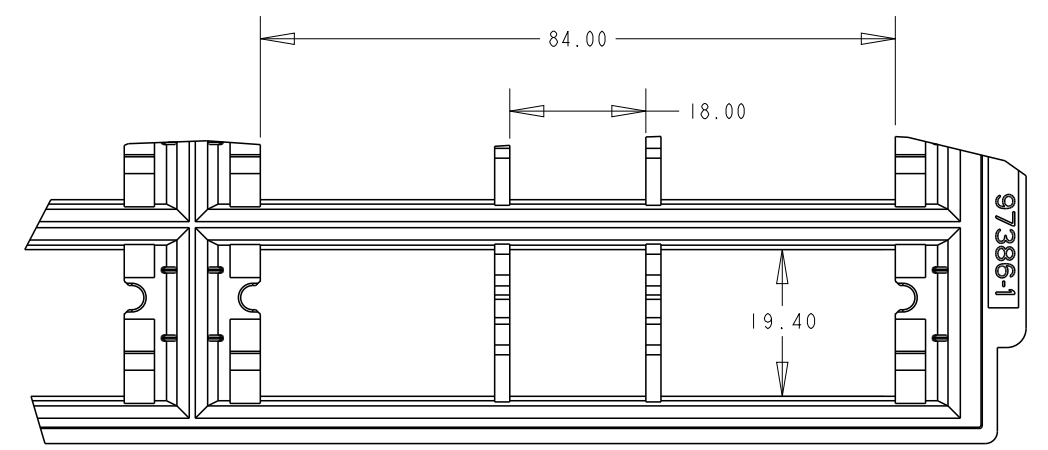
LOC	DIST	REVISIONS				
P	LTR	DESCRIPTION	DATE	DWN	APVD	
DY	-	SEE SHEET 1	-	-	-	



SCALE 1:5

Base of centre pocket is solid.

SEE DETAIL A



DETAIL A  
SCALE 2:1

SECTION C-C

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DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±.25 1 PLC ±0.25 2 PLC ±0.13 3 PLC ±0.10 4 PLC ±. ANGLES ±1°	CHK YJ SEE	NAME ASSEMBLY, MINIDIMM, R/A, LF 0.60mm PITCH, 244 CKTS, DDR2/3		
MATERIAL	FINISH	APVD SF LEONG	PRODUCT SPEC 108-51091	SIZE A3	CAGE CODE 00779
		APPLICATION SPEC 114-51011	WEIGHT -	DRAWING NO C=1735438	
CUSTOMER DRAWING			SCALE 1:1	SHEET 5 OF 5	REV B5

## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

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